ABSTRACT

The invention relates to a method and a device for separating products mounted on a common substrate, from each other, along (a) cutting line(s). The products each comprise one or more chips present on said substrate and connecting means connected thereto, the connecting ends remote from the chip of which are provided with solder balls bonded thereto. The products are clamped down on a supporting element by using a sub-atmospheric pressure, and the supporting element and a rotary cutting blade are moved relative to each other along the intended cutting line so as to cut through the substrate. A liquid is supplied at the location of said cutting line on either side of the substrate.

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